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(54) COPPER CONDUCTOR PASTE FOR ALUMINUM NITRIDE BOARD, AND ALUMINUM NITRIDE BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a copper conductor paste which adheres satisfactorily even to an aluminum nitride board and provide such an aluminum nitride board using the copper conductor paste.

SOLUTION: Particulates are formed from copper, copper oxide, or mixture thereof whose mean particle size ranges between 1-500 nm, and a mixture copper powder is prepared by adding to the particulates the base copper powder as chief component with the mean particle size ranging between 0.5-10 μ m and one sort or more of aux. copper powder having a smaller mean particle size, and therefrom a copper conductor paste is formed together with a binder resin, glass powder, and organic solvent, wherein the binder resin should consist of a resin having at least a pyrolytic temp. of 250-350°C, and the glass powder has a softening point lower than the sintering point of the particulates or mixture copper powder and higher than the decomposing temp. of the binder resin.

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